AMENDMENTS TO THE CLAIMS

The following listing of claims will replace all prior versions and listings of claims in the application.

LISTING OF CLAIMS

1. – 14. (Cancelled)

15. (Currently Amended) A method of manufacturing a circuit board~~, the circuit board~~ including a substrate ~~and the substrate including~~having an output side terminal, the method comprising:

~~a step of~~ solder mounting ~~a~~ first components within a pair of ~~a~~ first regions ~~and second regions~~ on the substrate ~~by a solder connection~~;

~~a step of~~ after mounting the first components, arranging an anisotropic conductive film within a band region of the substrate located between the pair of first regions, the band region having a major axis and a minor axis with the major axis being greater than the minor axis;

~~a step of~~ arranging a second component on the anisotropic conductive film; and

~~a step of~~ thermocompression-bonding the second component within a region of the band region using a compression bonding head with the anisotropic conductive film disposed between the second component and the band region,~~within a second region on the substrate with said anisotropic conductive film held therebetween~~;

wherein the band region extends toward the output side terminal such that the major axis of the band region is substantially perpendicular to the output side terminal. ~~said step of arranging said anisotropic conductive film within said band region of the~~

~~substrate is performed after said step of mounting the first component on the substrate by the solder connection;~~

~~said step of thermocompression bonding is performed with a compression bonding head; and~~

~~the band region is wider than the head, the band region extending from the second region toward the output side terminal along a longitudinal direction of a pressing surface of the head.~~

16. (Currently Amended) A method of manufacturing a circuit board according to claim 15, wherein ~~said step of~~ mounting ~~said~~of the first components on ~~said~~the substrate ~~by the solder connection~~ includes a reflow treatment.

17-20. (Cancelled)

21. (Currently Amended) A method of manufacturing a circuit board ~~in which components are mounted thereto, the circuit board~~ including an output side terminal disposed along an edge of the circuit board, the method comprising:

~~a.)~~ ~~selecting~~ arranging a band region on a surface of the circuit board between a pair of first regions, the band region having a major axis and a minor axis with the major axis being greater than the minor axis;

~~b.)~~ soldering a first component onto the circuit board in a first region located outside of the band region; and

c.) after step b.), mounting following soldering of the first component to the first region, thermocompression-bonding a second component to the circuit board a second component on the circuit board within a second second region located within the within the band region with using an anisotropic conductive film,

wherein step c.) includes a step of thermocompression-bonding the second component to the circuit board with and a compression bonding head where the band region is wider than the head; and

the band region is wider than the head, and

wherein the band region extends from the second region toward the output side terminal along a longitudinal direction of a pressing surface of the headsuch that the major axis of the band region is substantially perpendicular to the output side terminal.

22. (Currently Amended) The method of claim 21 where step c.)wherein the thermocompression-bonding is performed with a heated compression bonding head, and

wherein the band region is selected to correspond generally to the areas over which the head travels during step c.) thereby preventingto prevent impact of the head with the first component and isolating the first component from the heat generated by the head.

23. (Currently Amended) The method of claim 15, wherein the first components ~~is~~ are selected from the group of passive and mechanical components, and the second component comprises a semiconductor device.

24. (Cancelled)

25. (Previously Presented) The method of claim 15, wherein alignment marks are provided outside the band region.

26. (Previously Presented) The method of claim 15, wherein the bonding region is selected by performing a solder reflow process.

27. (Cancelled)

28. (Previously Presented) The method of claim 23, wherein the second component is selected from the group of a power source IC and a power source LSI.

29. (Previously Presented) The method of claim 15, wherein the band region extends from one end of the substrate to another end of the substrate.

30. (Previously Presented) The method of claim 15, wherein the band region extends rectilinearly along the substrate.

31. (Previously Presented) The method of claim 15, further comprising: forming wiring patterns on the substrate in the band region.

32. (Previously Presented) The method of claim 15, further comprising: forming a dummy electrode at a position associated with the second component.

33-36. (Cancelled)

37. (Previously Presented) The method according to claim 21, wherein the band region is narrower than a surface of the circuit board.

38. (Currently Amended) ~~The~~ A method according to claim 37, the second regions ~~further comprising mounting another first component in another first region located outside of the band region, the another first region being~~is disposed on the surface of the circuit board on a side of the circuit board that ~~opposes~~ opposed the first regions.

39. (Cancelled)